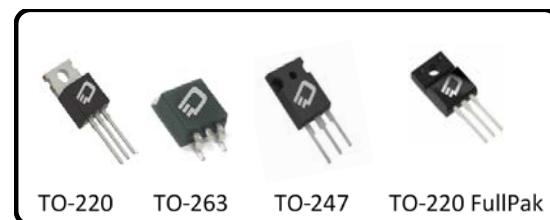


650V, 80mΩ, 40.8 Amp Super Junction Power

Ordering Information

Part Number	Package Option
D3S080N65B-U	TO-220
D3S080N65D-U	TO-247
D3S080N65E-U	TO-263
D3S080N65F-U	TO-220 FullPak

Package Options



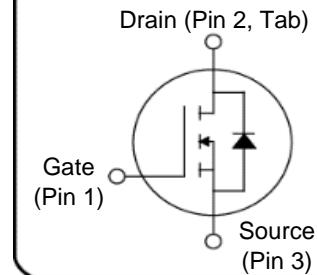
Description

+FET™ is an advanced Super Junction Power MOSFET offering excellent efficiency through low R_{DS(ON)} and low gate charge. +FET™ is a rugged device with precision charge balance implementation designed for demanding uses such as enterprise power computing power supplies, motor control, lighting and other challenging power conversion applications.

Features

- LOW R_{DS(ON)}
- FAST SWITCHING
- HIGH E_{AS}
- REL TEST SPEC: JESD-22
- HTRB >3000 HRS

Device Schematic



Benefits

- LOW CONDUCTION LOSSES
- HIGH EFFICIENCY
- EXCELLENT AVALANCHE PERFORMANCE

Table 1 Key Parameters

Parameter	Value	Unit
V _{DSS} @ T _{jmax}	710	V
RDS(on) max	< 80	mΩ
Qg typ	77	nC
I _D @ 25 °C	40.8	A

Applications

- POWER FACTOR CORRECTION
- SERVER POWER SUPPLIES
- TELECOM POWER SUPPLIES
- INVERTERS
- MOTOR CONTROL

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Maximum Ratings

Parameter	Symbol	Values			Unit	Condition
		Min	Ty p	Max		
				TO220, TO247, TO263		
Continuous drain current	I _D			40.8	20.3	A T _c = 25°C
				25.8	12.8	A T _c = 100°C
Pulsed drain current	I _D , pulse			175	81	A T _c = 25°C
Avalanche energy, single pulse	E _{AS}			650	650	mJ I _D = 7.2A; V _{DD} = 50V, V _{GS} = 10V, L=10mH, RG=25 Ohms
Avalanche energy, repetitive	E _{AR}			1	1	mJ I _D = 7.2; V _{DD} = 50V
Avalanche current, repetitive	I _{AS}			8.7	8.7	A
MOSFET dv/dt ruggedness	dv/dt			50	50	V/ns V _{DS} = 0....480V
Gate source voltage (static)	V _{GS}	-30		30	30	V Static
Gate source voltage (dynamic)	V _{GS}	-30		30	30	V AC (F>1Hz)
Power dissipation	P _{tot}			305	60	W T _c = 25°C
Storage temperature	T _{stg}	-55		150	150	°C
Operating junction temperature	T _j	-55		150	150	°C
Mounting torque				60	N-cm	M3 and M3.5 screws
				50	N-cm	M3 screw
Isolation Voltage*	V _{ISO}	3.5			kV	TO-220 FullPak Only
Continuous diode forward current	I _{SD}			43.6	20.3	A T _c = 25°C
Diode pulse current	I _S , pulse			175	81	A T _c = 25°C
Reverse diode dv/dt	dv/dt			15	15	V/ns V _{DS} =0...480V, I _{SD} <=I _S , T _j = 25°C
Maximum diode commutation speed	dI _f /dt			500	500	A/μs V _{DS} =0...480V, I _{SD} <=I _S , T _j = 25°C

Thermal Characteristics

Table 3 Thermal Characteristics

Symbol	Parameter	Packages				Unit
		TO-220	TO-263	TO-247	TO-220FP	
R _{thjC}	Thermal resistance, junction-case	0.41	0.41	0.41	1.89	°C/W
R _{thjA}	Thermal resistance, junction-ambient	42	42	42	44	°C/W
R _{thjT}	Thermal resistance, junction-ambient for SMD version		30			°C/W
T _s	Soldering temperature, wavesoldering only allowed at leads	260	260	260	260	°C

Electrical Characteristics

@ $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 4

Parameter	Symbol	Values			Unit	Condition
		Min	Typ	Max		
Drain-source breakdown voltage	V_{DSS}	650			V	$I_D = 1\text{mA}$, $V_{GS} = 0\text{V}$
Gate threshold voltage	$V_{(GS)th}$	2.3	3	3.7	V	
Zero gate voltage drain current	I_{DSS}			1	μA	$V_{DS} = 650\text{V}$, $T_c = 25^\circ\text{C}$
				50		$V_{DS} = 650\text{V}$, $T_c = 125^\circ\text{C}$
Gate-source leakage current	I_{GSS}			100	nA	
Drain-source on-state resistance	$R_{DS(on)}$		0.062	0.080	Ω	$V_{GS} = 10\text{V}$, $I_D = 15.9\text{A}$, $T_c = 25^\circ\text{C}$
	$R_{DS(on)}$		0.183			$V_{GS} = 10\text{V}$, $I_D = 10 \text{ A}$, $T_c = 150^\circ\text{C}$
Gate resistance	R_G		1		Ω	

Table 5

Parameter	Symbol	Values			Unit	Condition
		Min	Typ	Max		
Input capacitance	C_{iss}		4240		pF	$V_{DS} = 100\text{V}$, $f = 1\text{MHz}$, $V_{GS} = 0\text{V}$
Output capacitance	C_{oss}		97.5		pF	
Reverse transfer capacitance	C_{rss}		16.5		pF	
Turn-on delay time	$t_{d(on)}$		17		ns	$V_{DD} = 400\text{V}$, $I_D = 15.9\text{A}$ $R_G = 1\Omega$, $V_{GS} = 10\text{V}$
Rise time	t_r		24		ns	
Turn-off delay time	$t_{d(off)}$		90		ns	
Fall time	t_f		23		ns	

Table 6 Gate Charge Characteristics

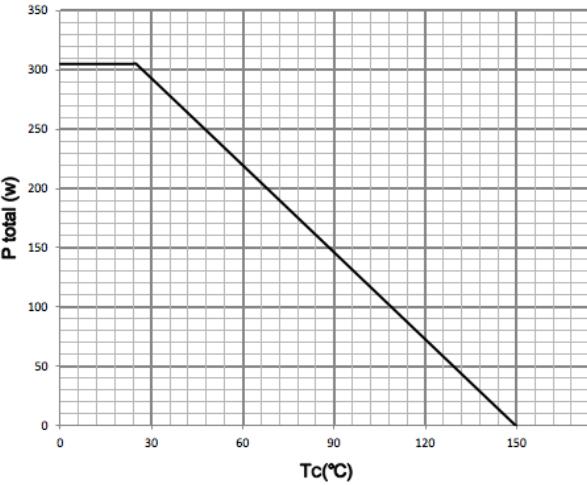
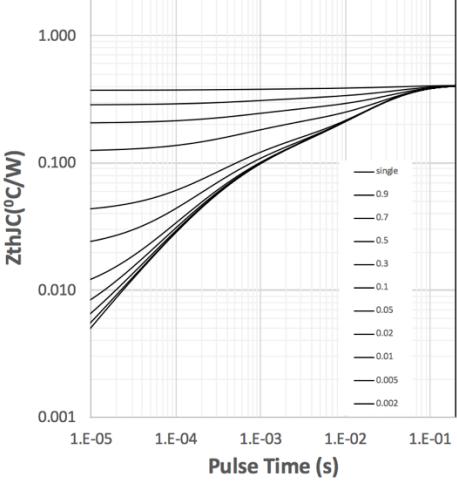
Parameter	Symbol	Values			Unit	Condition
		Min	Typ	Max		
Gate to source charge	Q_{gs}		16		nC	$V_{DD} = 480V$, $I_D = 15.9A$, $V_{GS} = 10V$
Gate to drain charge	Q_{gd}		27		nC	
Gate charge total	Q_g		77		nC	
Gate plateau voltage	$V_{plateau}$		5		V	

Table 7 Body Diode

Parameter	Symbol	Values			Unit	Condition
		Min	Typ	Max		
Diode source-drain current	I_{SD}			43.6	A	
Diode forward voltage	V_{fd}		0.95	1.5	V	$I_{SD} = 31.8A$, $V_{GS} = 0V$
Reverse recovery time	t_{rr}		468		ns	$I_{SD} = 31.8A$, $di/dt = 100A/\mu S$ $V_{DD} = 60V$, $T_c = 25^\circ C$
Reverse recovery charge	Q_{rr}		9.5		μC	
Peak reverse recovery current	I_{rrm}		50.0		A	

Electrical Characteristics Graphs

Table 8 Thermal Performance

Power Dissipation TO220, TO247, TO263	Maximum Transient Thermal Impedance
	
Max power limited by case temperature	Variable is pulse time (t_p) TO220, TO247, TO263

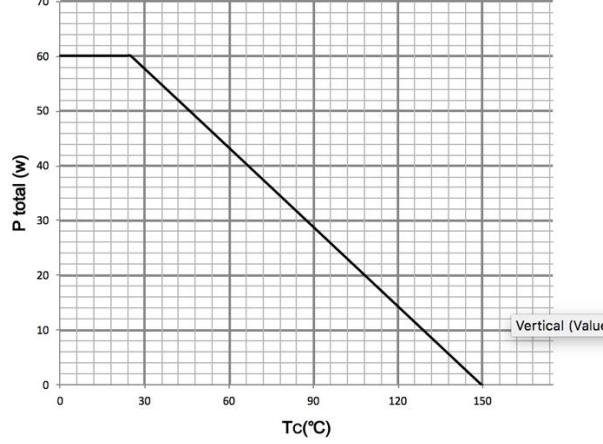
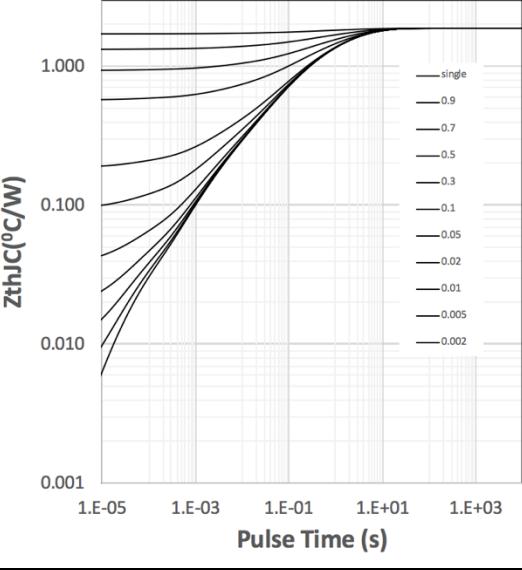
Power Dissipation TO220FP	Maximum Transient Thermal Impedance (TO220FP)
	
Max power limited by case temperature	Variable is pulse time (t_p) TO220FP

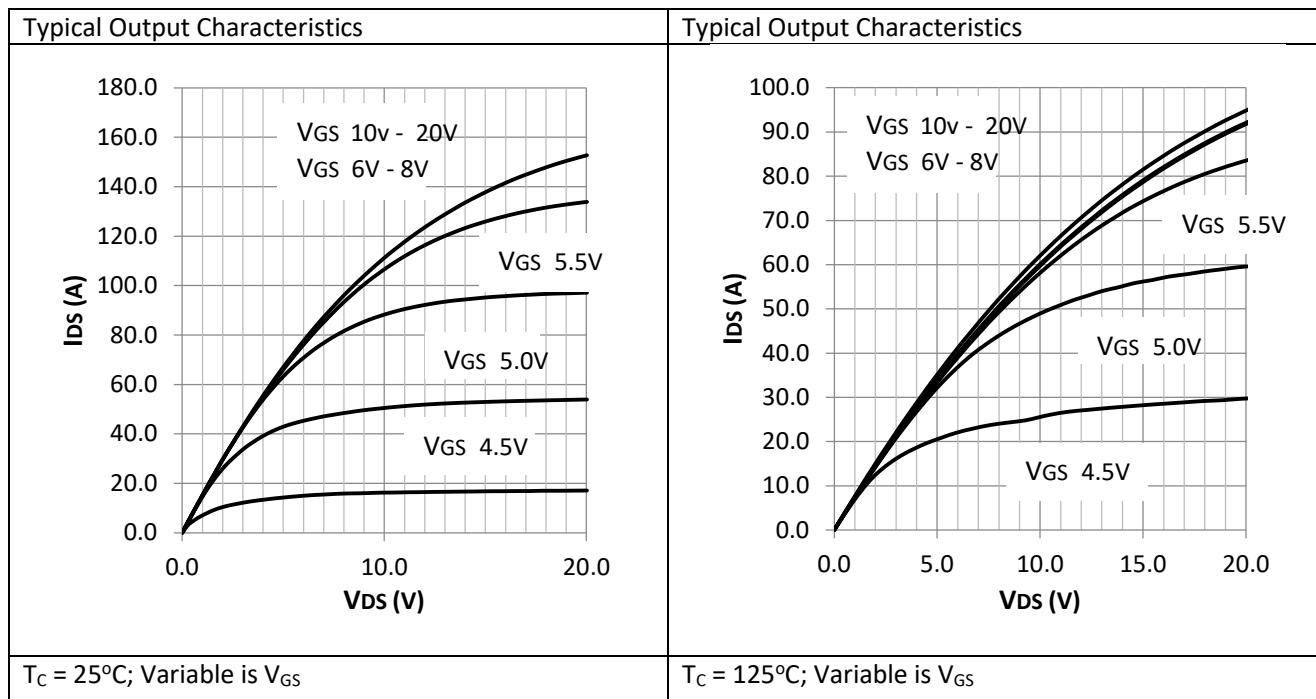
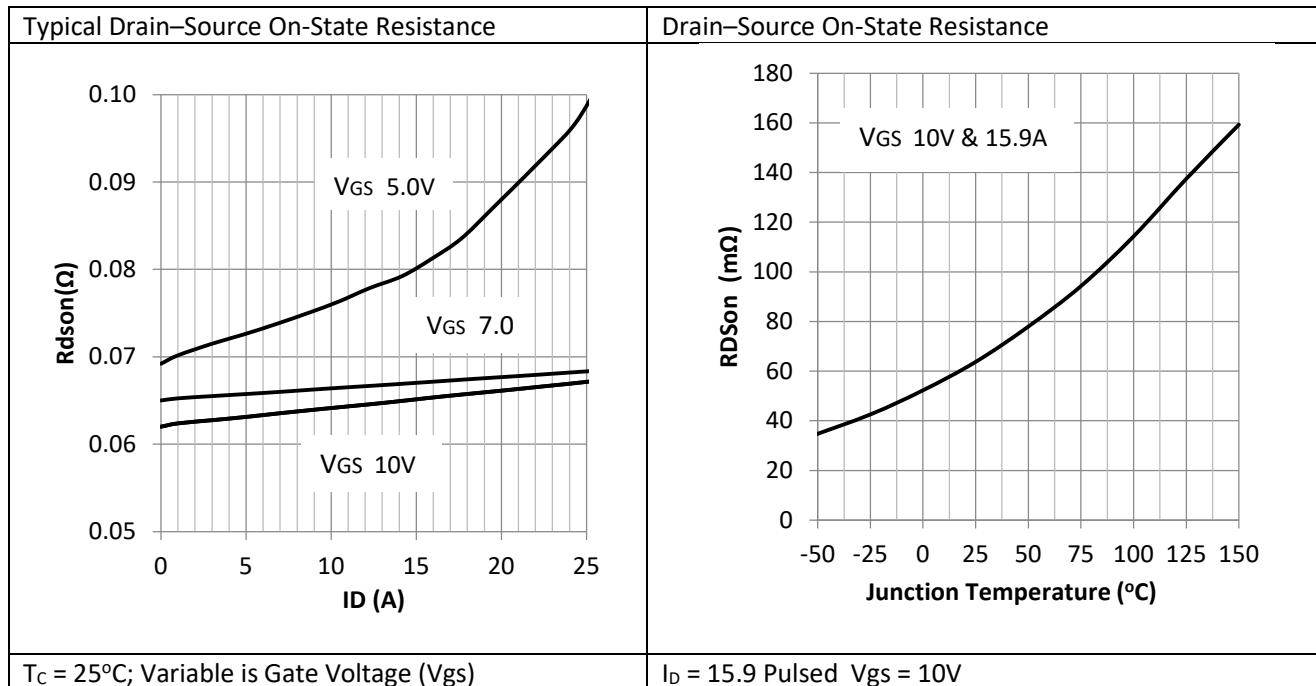
Table 9 Output Characteristics

Table 10 Drain-Source Resistance


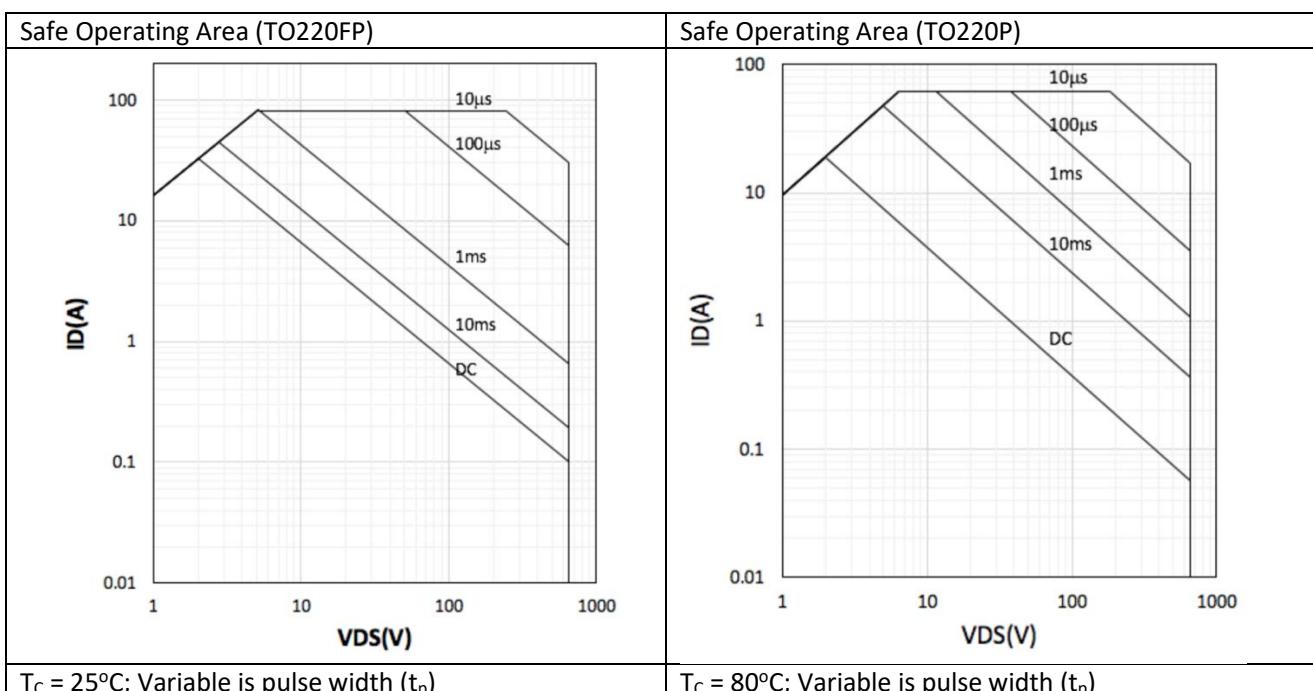
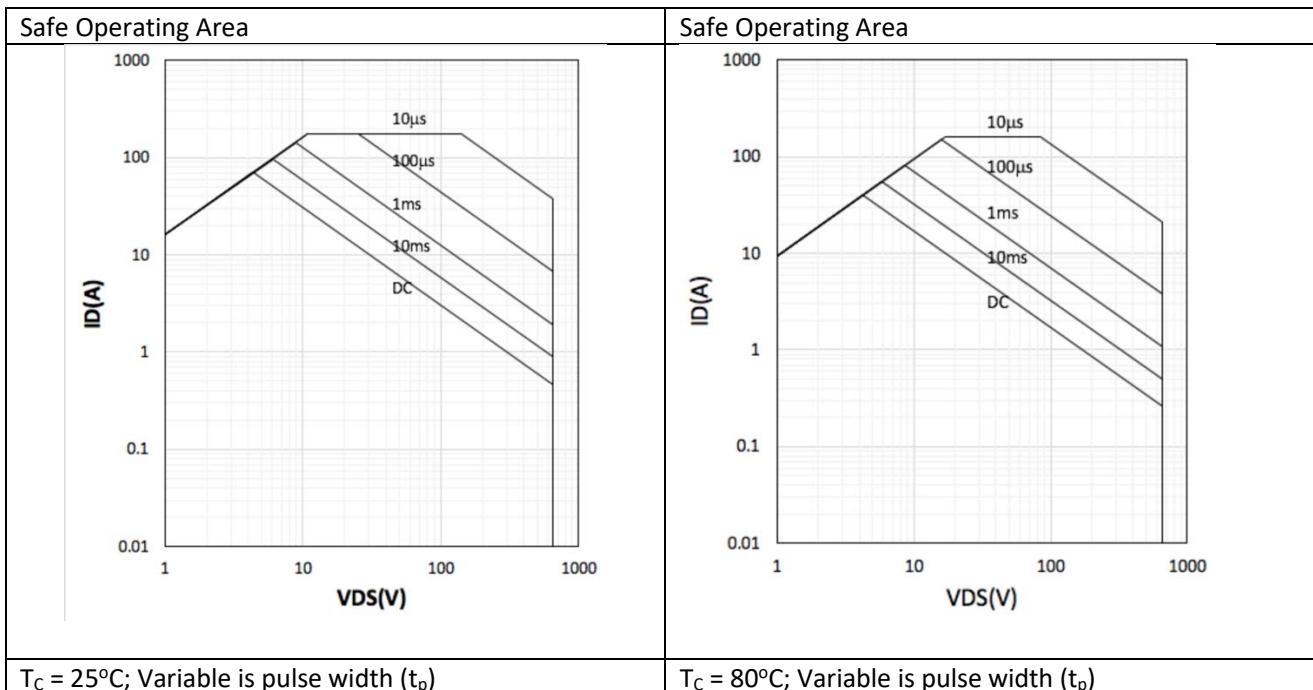
Table 11 Safe Operating Area


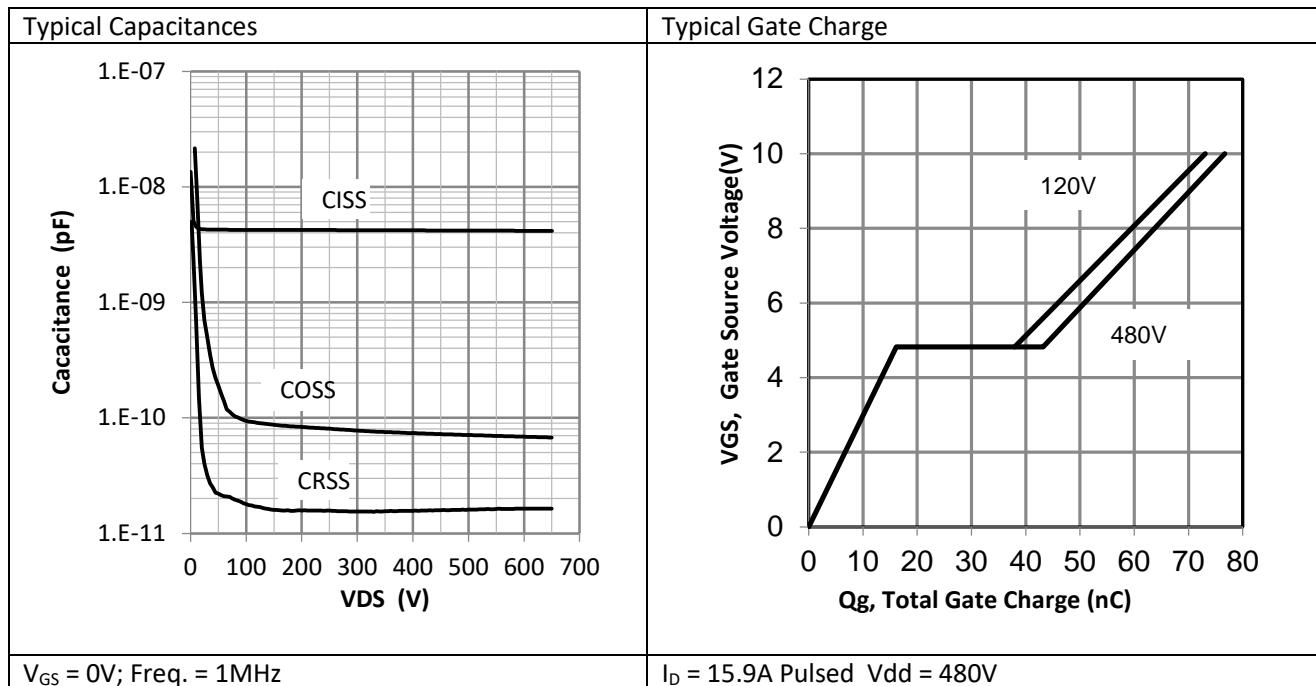
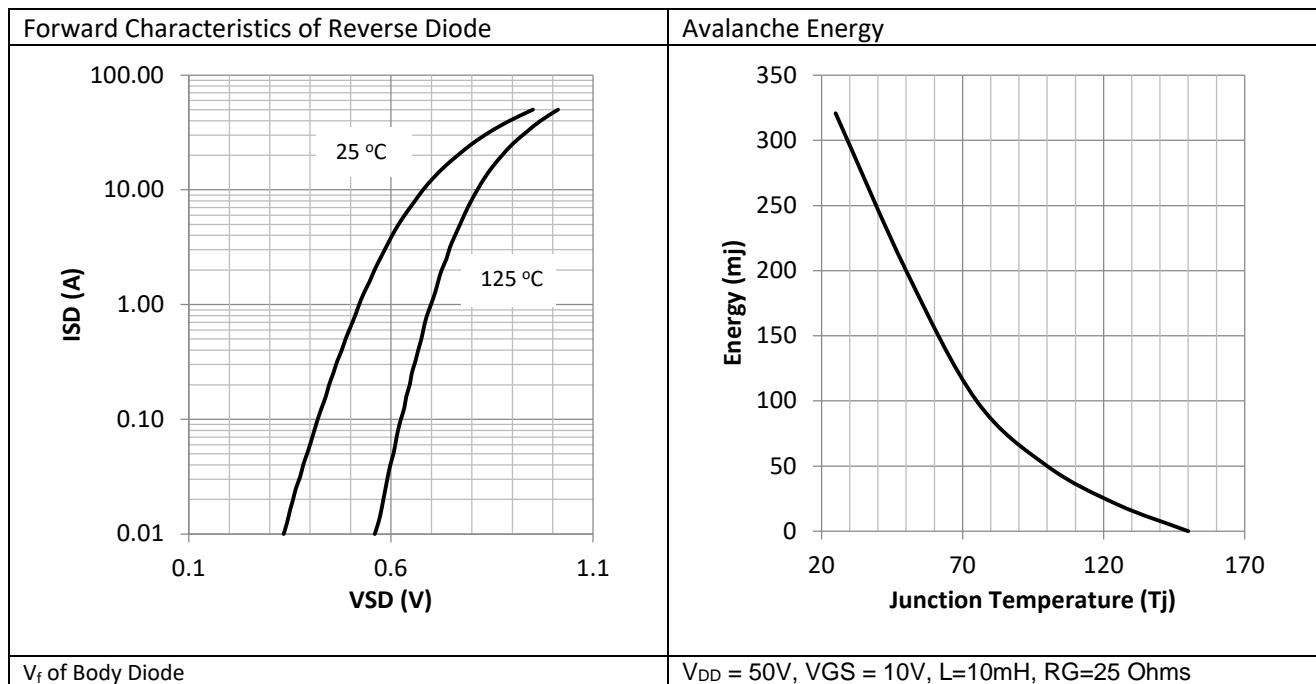
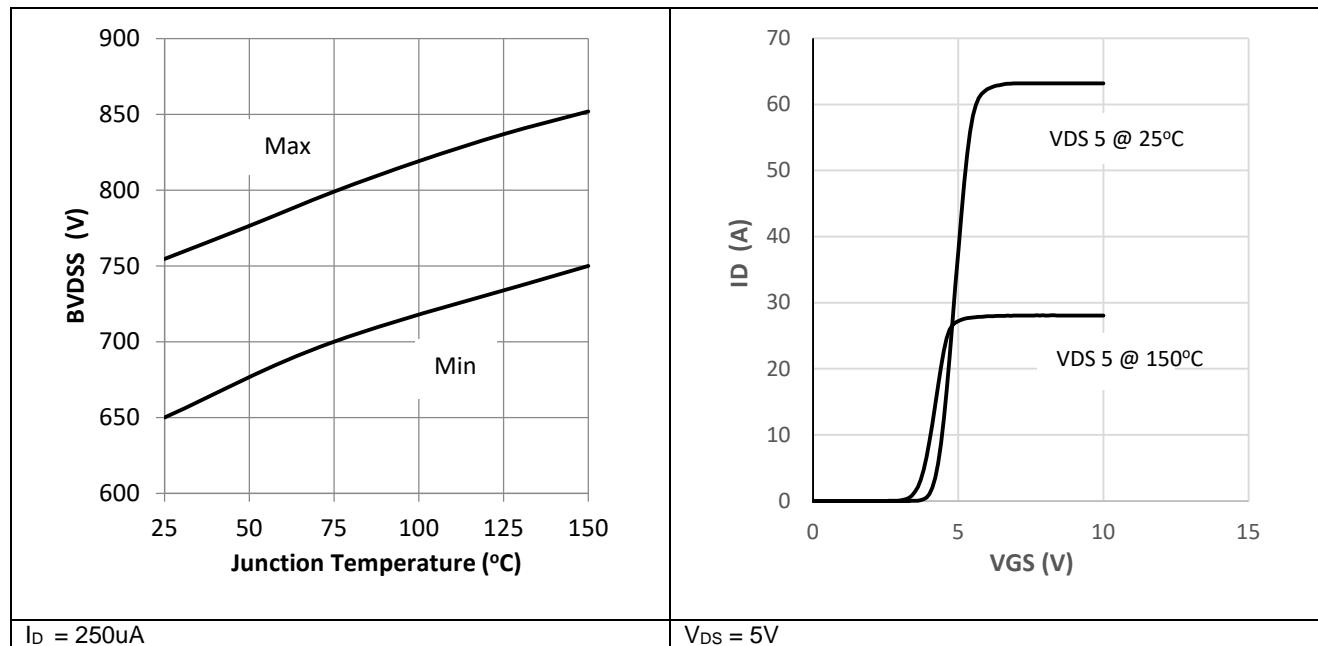
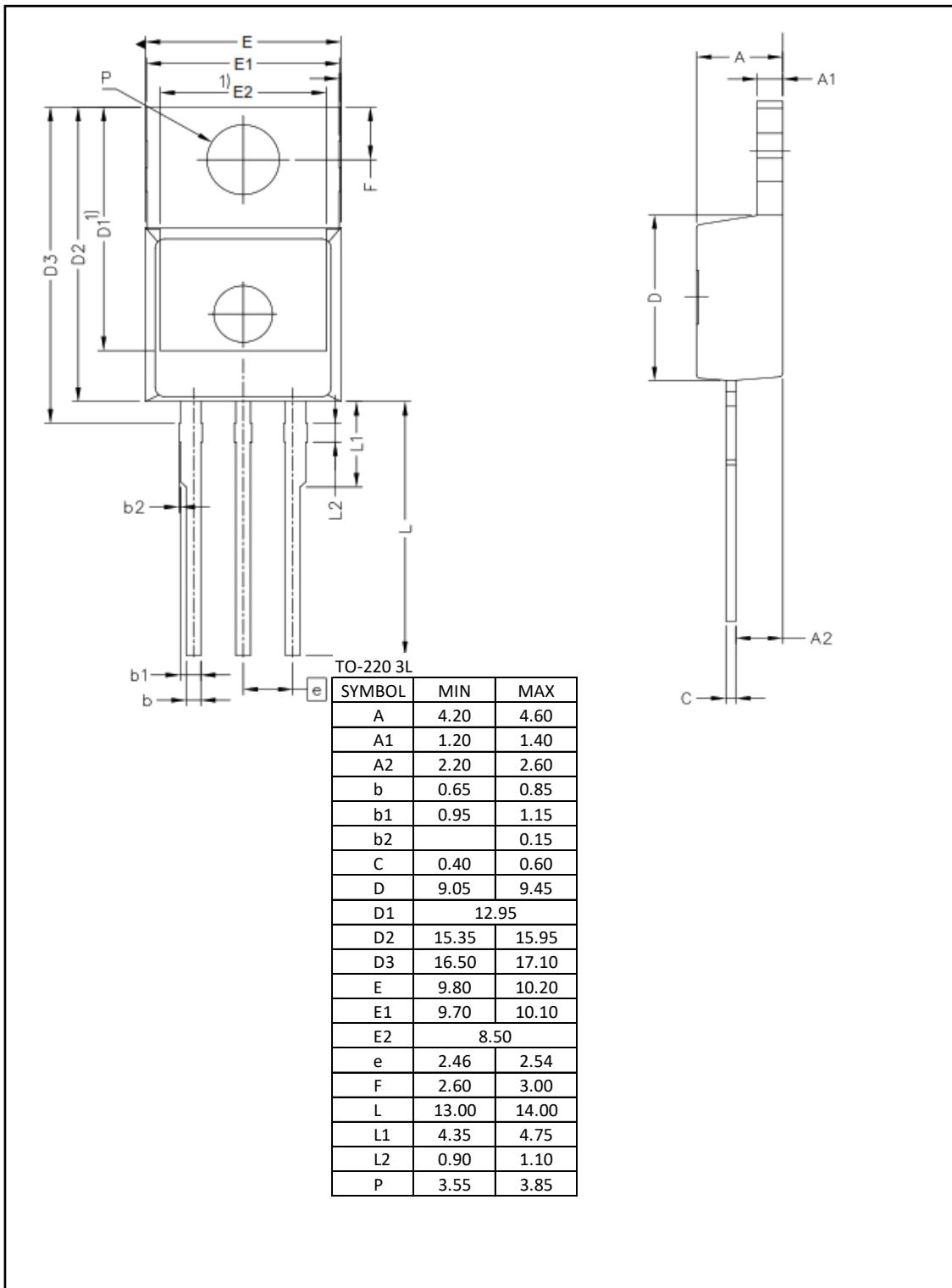
Table 12 Typical Capacitances and Gate Charge

Table 13 Diode Forward Characteristics and Avalanche Energy


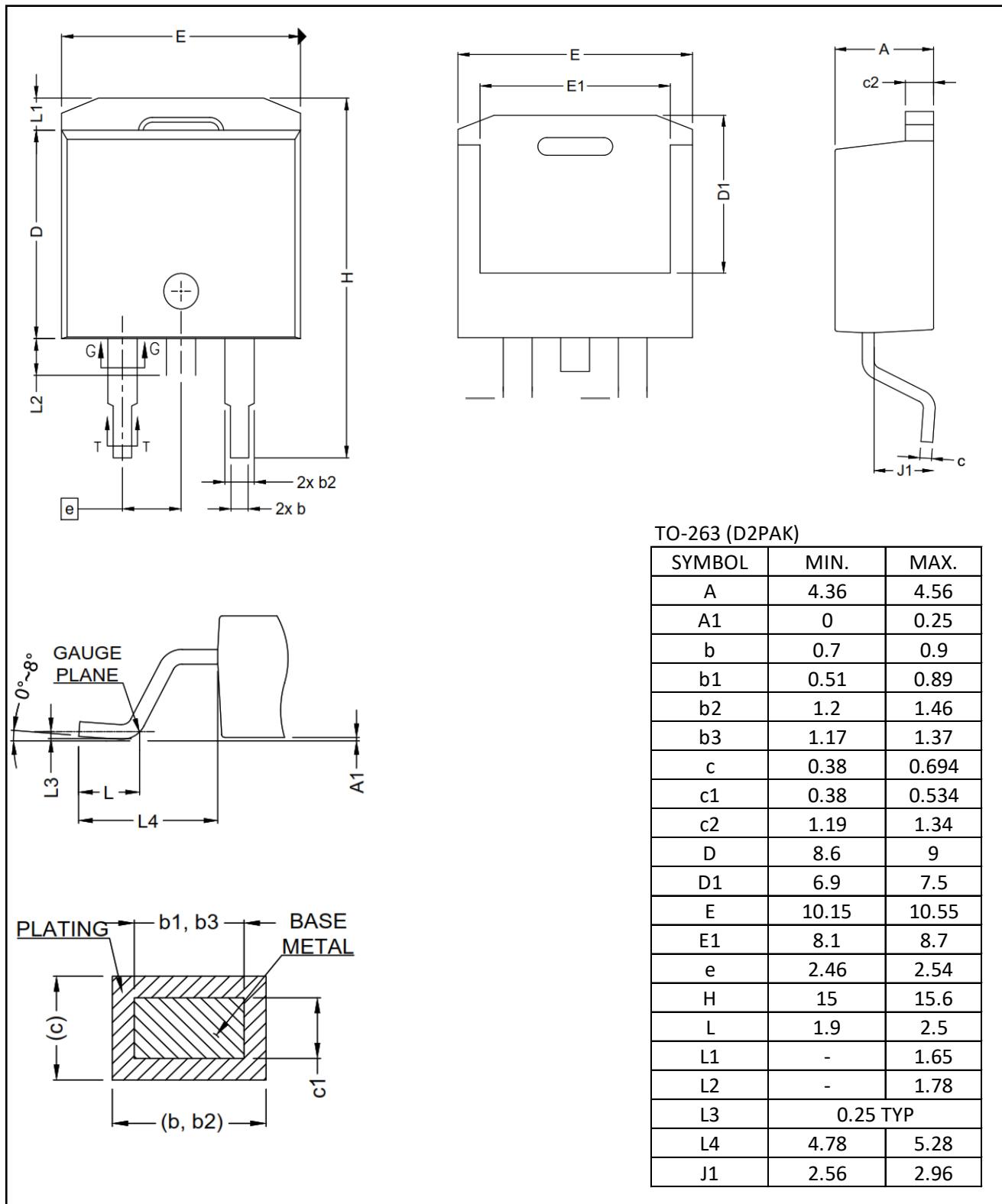
Table 14 Drain – Source Breakdown Voltage and Typical Transfer Characteristics



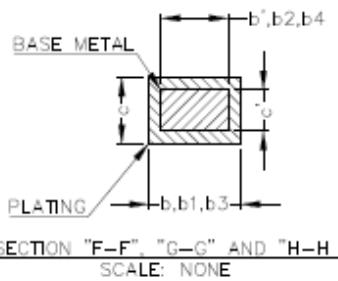
D3 Semiconductor TO-220-3L



D3 Semiconductor TO-263 (D2PAK)

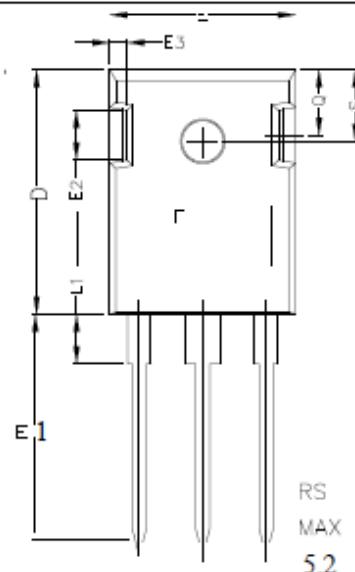


D3 Semiconductor TO-247-3L

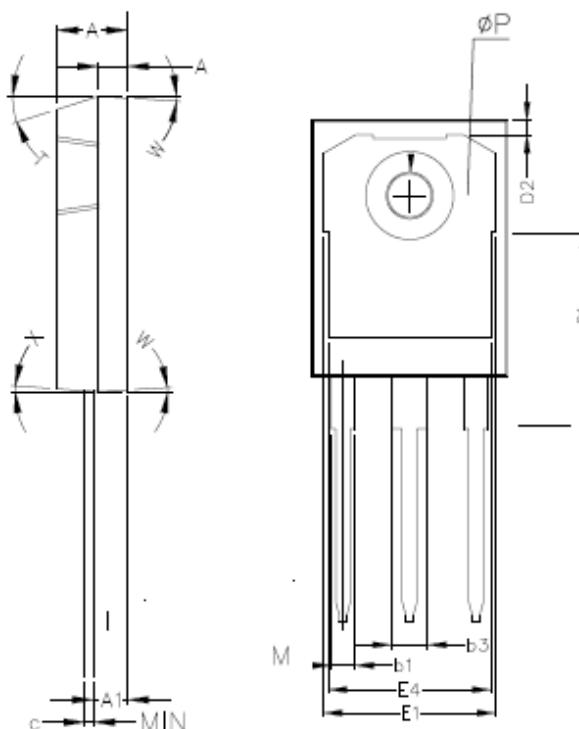


1. ALL METAL SURFACES: TIN PLATED, EXCEPT AREA OF CUT
 2. DIMENSIONING & TOLERANCING CONFIRM TO
 ASME Y14.5M-1994.
 3. ALL DIMENSIONS ARE IN MILLIMETERS.
 ANGLES ARE IN DEGREES.
 4. THIS DRAWING WILL MEET ALL DIMENSIONS REQUIREMENT
 OF JEDEC outlines TO-247 AD.

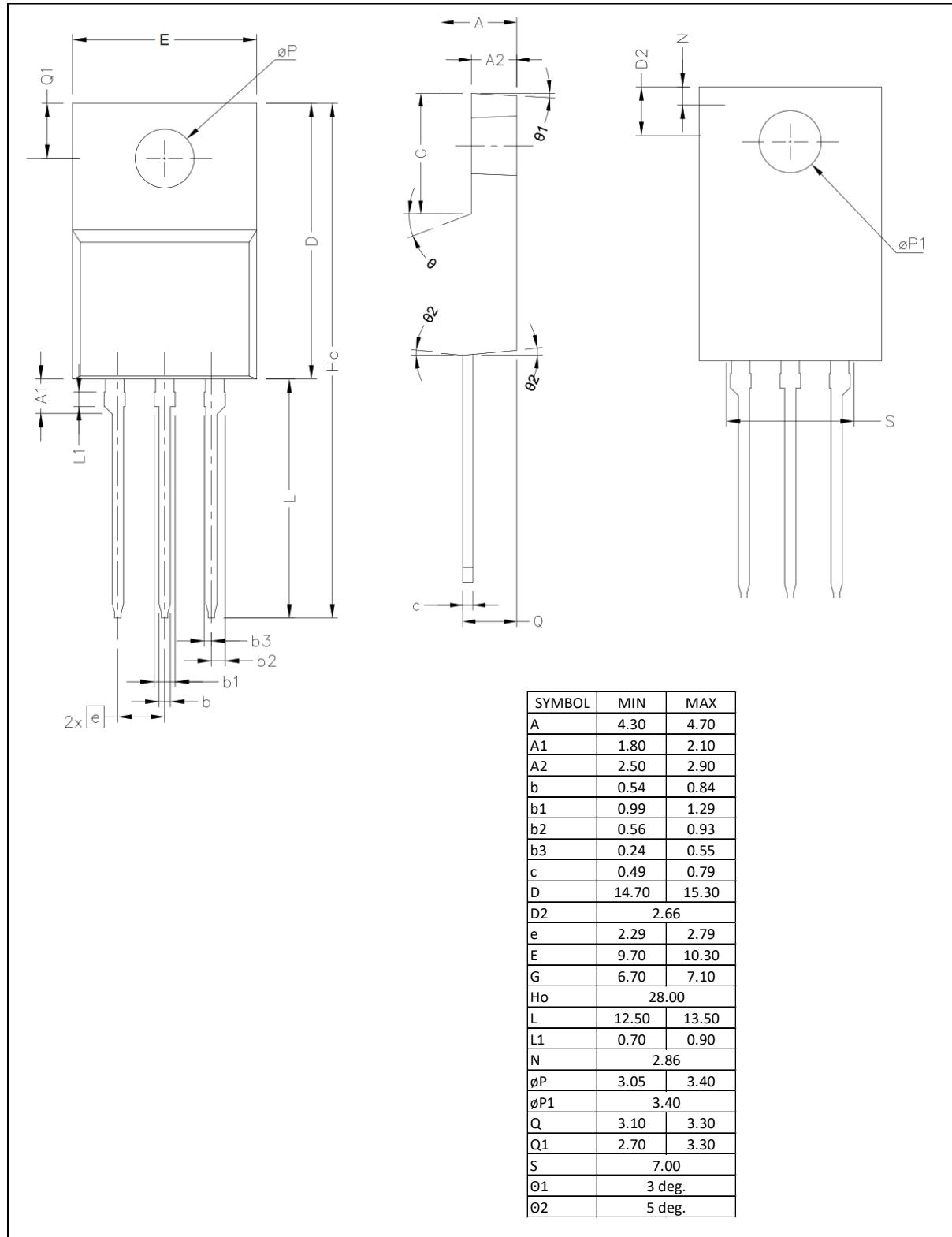
SYM	MILLIMETERS	
	MIN	MAX
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b'	1.07	1.28
b	1.07	1.33
b1	1.91	2.41
b2	1.91	2.16
b3	2.87	3.38
b4	2.87	3.13
c'	0.55	0.65
c	0.55	0.68
D	20.80	21.10
D1	16.25	17.65
D2	0.95	1.25
E	15.75	16.13
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e	5.44 BSC	
N	3	
L	19.81	20.32
L1	4.10	4.40
øP	3.51	3.65
Q	5.49	6.00
S	6.04	6.30
T	17.5° ref	
W	3.5° ref.	
X	4° ref	



- 1 - GATE
 2 - DRAIN (COLLECTOR)
 3 - SOURCE (EMITTER)
 4 - DRAIN (COLLECTOR)



D3 Semiconductor TO-220 FullPak



Revision History

Revision	Release Date	Comments
1.0	1-June-2016	Preliminary Datasheet Draft
1.1	1-Nov-2017	Datasheet Characterization Update
1.2	23-Nov-2018	Correct TO263 to E (Tape & Reel)
2.0	18-APR-2019	Update Characterizaton

Resources

www.d3semi.com

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[TPCC8103,L1Q\(CM](#) [MIC4420CM-TR](#) [VN1206L](#) [614234A](#) [715780A](#) [NTNS3166NZT5G](#) [SSM6J414TU,LF\(T](#) [751625C](#)
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